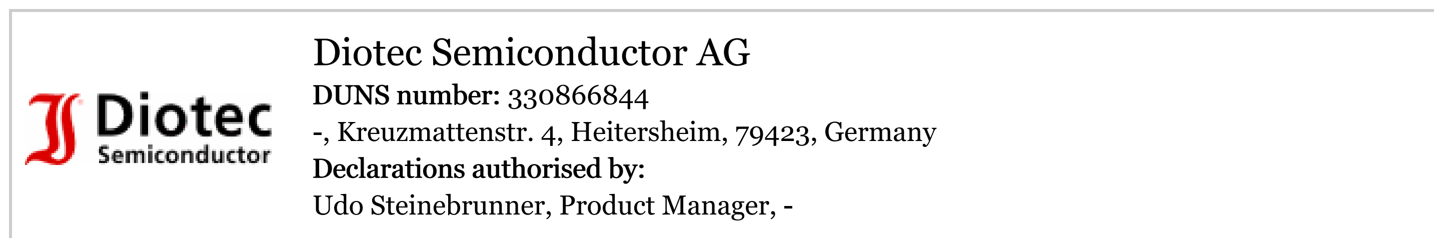
BOMcheck.net

Full Material Declaration for attached parts list

Report generated: 06 February 2026, 13:57 GMT



Diotec Semiconductor AG

DUNS number: 330866844
-, Kreuzmattenstr. 4, Heitersheim, 79423, Germany
Declarations authorised by:
Udo Steinebrunner, Product Manager, -

Declaration effective from: 01 January 2014 [Approved on 06 February 2026, 13:55 GMT]

Materials and substances

Use/Location	Material Group	% w/w of material in the part	Substances in the material	CAS Number	% w/w of substance in the material
Chip (die)	Other inorganic materials	0.55%	Silicon	7440-21-3	100%
Encapsulation	EP (Epoxy resin)	72.4%	Carbon black	1333-86-4	0.8%
			Silicon Dioxide	7631-86-9	2.5%
			Phenol, polymer with formaldehyde	9003-35-4	3.7%
			Magnesium hydroxide (Mg(OH)2)	1309-42-8	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	6%
			Quartz sand	60676-86-0	82%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.09%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	0.56%	Tin	7440-31-5	100%
Leadframe	Steel and iron materials	26.4%	SILVER, ELEMENTAL	7440-22-4	1.2%
			Iron nickel zinc oxide REACH Article 67 Exemption	12645-50-0	98.8%

Attached parts list

Part number	Part name	Part Mass	Part Mass UoM
SOD-123 (H) Pb&H-free Cu	Diode SMD	0.00915	g